

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Hsu, et al.

Serial No.: 09/739,139

Confirmation No.: 4854

Filed: December 18, 2000

For: Integrated Multi-Step Gap
Fill And All Feature
Planarization For
Conductive Materials

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:



Group Art Unit: 1763

Examiner: MacArthur, Sylvia

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2/6/03
MW

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CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on January 27, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231	
Date 1/27/03	Signature

PETITION FOR TWO-MONTH EXTENSION OF TIME

Applicant respectfully petitions the Commissioner under 37 CFR 1.136(a) to grant a two-month extension of time to and including January 28, 2002, in which to file the response to the Office Action dated August 28, 2002.

This form is filed in duplicate. The Commissioner is authorized to charge the fee of \$400.00 and any additional fees, including excess claim fees, which may be required for this submission to Deposit Account No. 20-0782/AMAT/5614.

Respectfully submitted,

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